



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-05-11
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	SD07*0402BUY	A	BO2A	2017-05-11
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.9x3.9x1.75	8	gull wing	
Comment	Package: 07 SO 08 .15 JEDEC; MDF valid for TS512BIYDT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	SD07*0402BUY				500000.0	1000005.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.419	mg	supplier	die	Silicon (Si)	7440-21-3		2.366	mg	978090	29575
				supplier	metallization	Aluminium (Al)	7429-90-5		0.029	mg	11988	363
				supplier	Passivation	Silicon Nitride	12033-89-5		0.010	mg	4134	125
				supplier	Passivation	Silicon Oxide	7631-86-9		0.014	mg	5788	175
Leadframe	Copper & its alloys	29.130	mg	supplier	alloy	Copper (Cu)	7440-50-8		28.245	mg	969619	353063
				supplier	alloy	Iron (Fe)	7439-89-6		0.664	mg	22794	8300
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.040	mg	1373	500
				supplier	alloy	Zinc (Zn)	7440-66-6		0.035	mg	1202	438
				supplier	metallization	Nickel (Ni)	7440-02-0		0.134	mg	4600	1675
				supplier	metallization	Palladium (Pd)	7440-05-3		0.004	mg	137	50
				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	137	50
				supplier	metallization	Silver (Ag)	7440-22-4		0.004	mg	137	50
Die attach	Other Organic Materials	0.871	mg	supplier	glue	Silver (Ag)	7440-22-4		0.764	mg	877153	9550
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.044	mg	50517	550
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.044	mg	50517	550
				supplier	glue	Acrylate polymer	87320-05-6		0.017	mg	19518	213
				supplier	glue	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3		0.001	mg	1148	13
				supplier	glue	tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	1148	13
Bonding wires	Other inorganic materials	0.062	mg	supplier	wire	Copper (Cu)	7440-50-8		0.062	mg	1000000	775
Encapsulation	Other Organic Materials	47.518	mg	supplier	mold compound	Silica, vitreous	60676-86-0		41.151	mg	865998	514383
				supplier	mold compound	Epoxy Resin	25068-38-6		3.564	mg	75001	44549
				supplier	mold compound	Phenol Resin	29690-82-2		2.376	mg	50000	29699
				supplier	mold compound	Carbon black	1333-86-4		0.238	mg	5000	2970
				supplier	mold compound	Bismuth compound	7440-69-9		0.190	mg	4001	2376